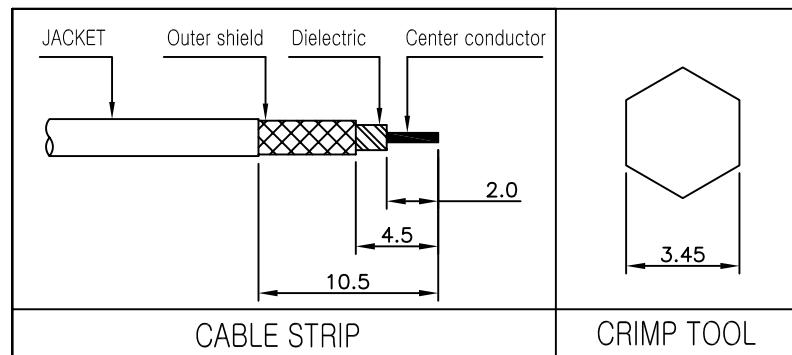
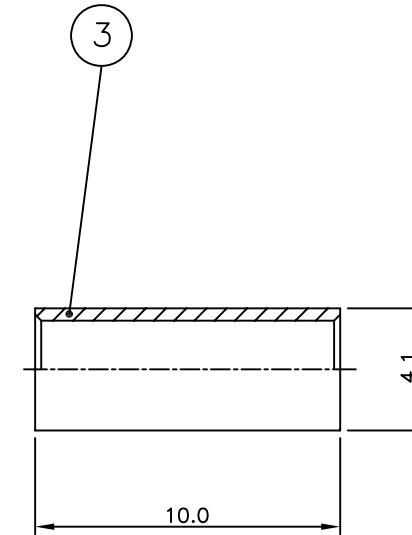
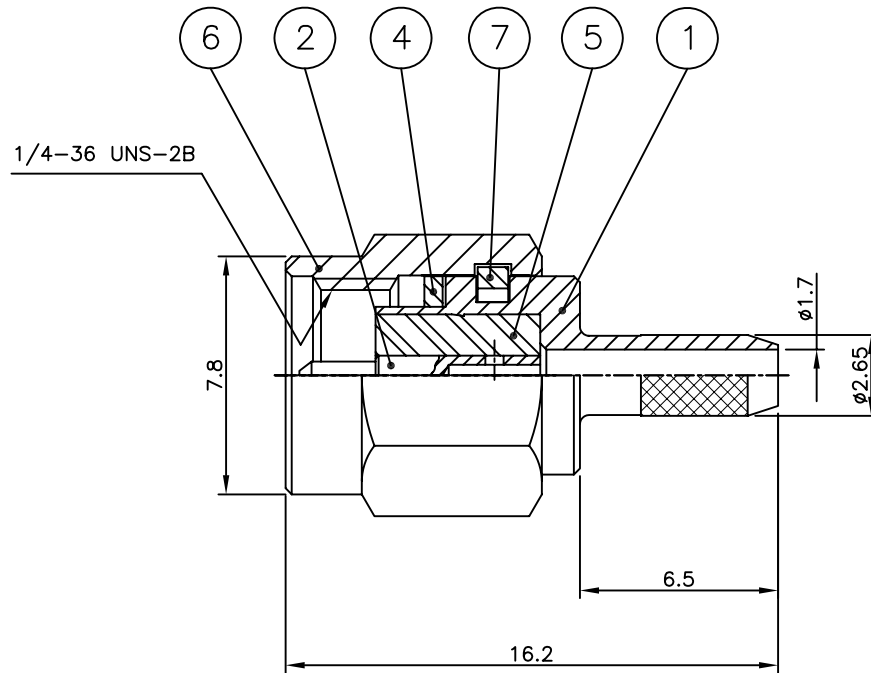


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	H.J.LEE	I.C.KIM	2015.11.03.
1	고객사 커넥터 압착부 바디 부러짐 현상 개선으로 인한 R추가	S.Y.EUN	I.C.KIM	2020.12.08.



7	SPRING RING	1	Pasivated	부동태처리	DSR00002-5/1 (R2001)
6	COUPLING CAP	1	Pasivated	부동태처리	DCU00006-5/1 (K2001)
5	INSULATOR	1	TEFLON		DIN01667-N/1
4	GASKET	1			DGK00004-N/1 (G2001)
3	FERRULE	1	MBsBD	Gold Plate	DFE00041-5/1
2	CONTACT	1	MBsBD	Gold Plate	DCT00292-5/1 (E2001)
1	BODY	1	MBsBD	Gold Plate	DBD00128-5/4 DBD00128-5/2
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2020. 12. 08.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL	-	CHECKED BY		KJ COMTECH CO.,LTD. TITLE SMA50 CABLE PS RG316DS
		DRAWN BY	S.Y.EUN	
FINISH	-	SCALE	4/1	DWG NO. CN00962-7/5 REVISION 1 SHEET 1 of 1
		UNIT	mm	